



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

06-OCT-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13699

TITLE: SOT-723 Assembly/Test Qualification at Leshan

EFFECTIVE DATE: 06-Feb-2005

AFFECTED CHANGE CATEGORY:
ON Semiconductor Assembly/Test Site

AFFECTED PRODUCT DIVISION:
Discretes Products

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or Mark Dewitt <FFN96B@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce additional Assembly/Test capacity of SOT-723 manufacturing in our factory located in Leshan China. This notification affects NPN/PNP General Purpose Transistors and Digital Transistors. Our Leshan factory is both QS9000 certified and AEC qualified and has been producing all the technologies in SOT-23 for customers worldwide for many years. This expansion will provide additional flexibility and capacity needed to improve responsiveness and on time delivery to our valuable customers.

There will be no change to the form, fit, and function of the devices. Device parameters will continue to meet all Data Book specifications, and reliability will continue to meet or exceed ON Semiconductors standards.



Initial Product/Process Change Notification #13699

QUALIFICATION PLAN:

Package = SOT723, Devices, BAS16, BC846, MMBT2907A, DAN222

Test	Conditions	Interval	Sample Size (Lots x Units)
A/clave +PC	Ta=121 degC, P=15 psig, RH=100%	96 hrs	3x77
H3TRB+PC	Ta=85 degC, RH = 85%, Bias = 80% rated voltage	1008 hrs	3x77
HTB	Ta = 150 deg C	1008 hrs	3x77
HTRB	Ta=150 degC, bias = 80% rated voltage	1008 hrs	3x77
Temp Cycle +PC	Ta = -65 to +150 deg C	1000 cyc	3x77
IOL+PC	Ta=25 deg C, Ton=Toff=2min, delta Tj=100 deg C max	15000 cyc	3x77
MSL1 (PC)	24 hr bake @125deg C + 168 hr 85/85 Readout + 3 IR @ 260 deg C + 1x Flux immersion + Alcohol + DI rinse + Visual	3x252	

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

2SA2029M3T5G
 2SC5658M3T5G
 BC846BM3T5G
 BC856BM3T5G
 DTA114EM3T5G
 DTA114TM3T5G
 DTA114YM3T5G
 DTA115EM3T5G
 DTA123EM3T5G
 DTA123JM3T5G
 DTA124EM3T5G
 DTA124XM3T5G
 DTA143EM3T5G
 DTA143TM3T5G
 DTA143ZM3T5G
 DTA144EM3T5G
 DTA144TM3T5G
 DTA144WM3T5G
 DTC114EM3T5G
 DTC114TM3T5G
 DTC114YM3T5G
 DTC115EM3T5G
 DTC123EM3T5G
 DTC123JM3T5G
 DTC124EM3T5G
 DTC124XM3T5G



Initial Product/Process Change Notification #13699

DTC143EM3T5G
DTC143TM3T5G
DTC143ZM3T5G
DTC144EM3T5G
DTC144TM3T5G
DTC144WM3T5G